

SN74AVC8T245-Q1 構成可能な電圧レベル変換および3ステート出力搭載、車載用、8ビット、両電源、バス トランシーバ

1 特長

- 車載アプリケーション向けに認定済み
- AEC-Q100 テスト ガイダンスにおいて以下の結果:
 - デバイス温度グレード 1: -40°C ~ +125°C の動作時 周囲温度範囲
 - デバイス HBM ESD 分類レベル H2
 - デバイス CDM ESD 分類レベル C3B
- V_{CCA} 電圧基準の制御入力 V_{IH}/V_{IL} レベル
- V_{CC} 絶縁機能: いずれかの V_{CC} 入力が GND レベルになると、すべての出力が高インピーダンス状態に移行
- I_{off} により部分的パワーダウン モードでの動作をサポート
- 完全に構成可能なデュアル レール設計により、1.4V ~ 3.6V の電源電圧の全範囲にわたって各ポートが動作可能
- 4.6V 許容の I/O
- データレート (最大値):
 - 170Mbps ($V_{CCA} < 1.8V$ または $V_{CCB} < 1.8V$)
 - 320Mbps ($V_{CCA} \geq 1.8V$ および $V_{CCB} \geq 1.8V$)
- JESD 78, Class II 準拠で 100mA 超のラッチアップ 性能

2 アプリケーション

- テレマティクス
- クラスタ
- ヘッド・ユニット
- ナビゲーション システム

3 概要

SN74AVC8T245-Q1 は、設定可能な 2 本の独立した電源レールを採用した 8 ビット非反転バス・トランシーバです。SN74AVC8T245-Q1 の動作は V_{CCA} および V_{CCB} を 1.4V ~ 3.6V に設定して動作させるのが最適です。本デバイスは、 V_{CCA} および V_{CCB} がわずか 1.2V で動作します。A ポートは、 V_{CCA} をトラッキングするように設計されています。 V_{CCA} は 1.2V ~ 3.6V の電源電圧に対応します。B ポートは V_{CCB} に追従する設計で、 V_{CCB} には、1.2 V ~ 3.6V 範囲の任意の電源電圧を供給できます。このため、1.2V、1.5V、1.8V、2.5V、3.3V の任意の電圧ノード間で、低電圧の双方向レベル変換を自在に行うことが可能です。

SN74AVC8T245-Q1 の設計により、複数のデータ バス間の非同期通信が可能になります。このデバイスは、方向

制御 (DIR) 入力の論理レベルに応じて、A バスから B バス、または B バスから A バスへデータを転送します。出力イネーブル ($\overline{OE}$) 入力を使用して出力をディセーブルにすることにより、バスを実質的に絶縁できます。

SN74AVC8T245-Q1 の設計では、 V_{CCA} により制御ピン (DIR および $\overline{OE}$) に電力供給されます。

本デバイス仕様は、 I_{off} を使用した部分的パワーダウン アプリケーションを対象としています。 I_{off} 回路は、デバイスの電源がオフになったとき、出力をディセーブルにします。これによってデバイスへの電流の逆流を阻止し、デバイスを損傷から保護します。

この V_{CC} 絶縁機能により、いずれかの V_{CC} 入力が GND の場合、両方のポートを高インピーダンス状態にすることができます。

電源投入または電源オフの間にデバイスを高インピーダンス状態にするには、 $\overline{OE}$ をプルアップ抵抗を介して V_{CC} に接続します。この抵抗の最小値は、ドライバの電流シンク能力によって決まります。

パッケージ情報

部品番号	パッケージ(1)	パッケージ サイズ(2)
SN74AVC8T245-Q1	RHL (VQFN, 24)	5.5mm × 3.5mm
	PW (TSSOP, 24)	7.8mm × 6.4mm

- 詳細については、[セクション 11](#) を参照してください。
- パッケージ サイズ (長さ×幅) は公称値であり、該当する場合はピンも含まれます。

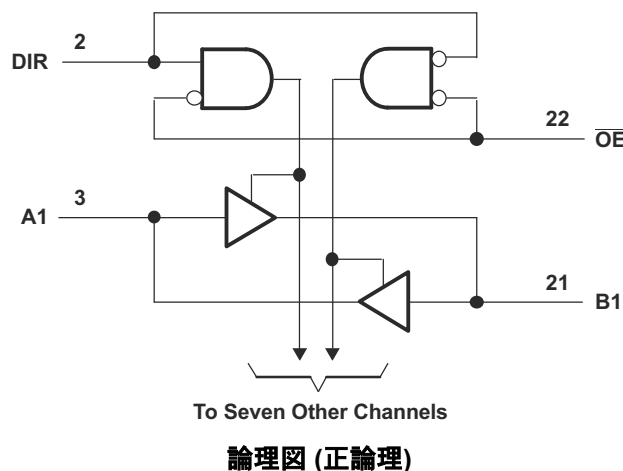


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4 Pin Configuration and Functions

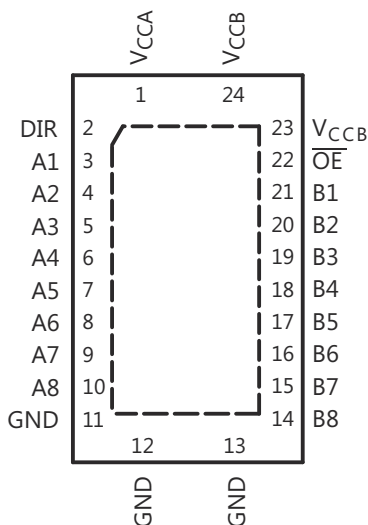


図 4-1. RHL Package, 24-Pin VQFN (Top View)

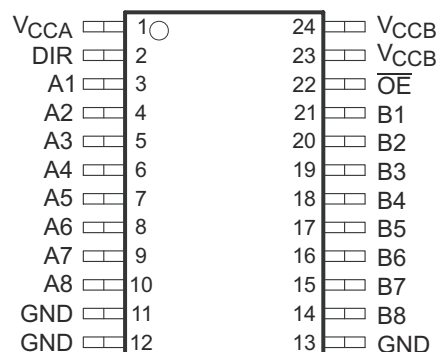


図 4-2. PW Package, 24-Pin TSSOP (Top View)

表 4-1. Pin Functions

PIN			TYPE ⁽¹⁾	DESCRIPTION
NAME	VQFN	TSSOP		
A1	3	3	I/O	Input/output A1. Referenced to V_{CCA} .
A2	4	4	I/O	Input/output A2. Referenced to V_{CCA} .
A3	5	5	I/O	Input/output A3. Referenced to V_{CCA} .
A4	6	6	I/O	Input/output A4. Referenced to V_{CCA} .
A5	7	7	I/O	Input/output A5. Referenced to V_{CCA} .
A6	8	8	I/O	Input/output A6. Referenced to V_{CCA} .
A7	9	9	I/O	Input/output A7. Referenced to V_{CCA} .
A8	10	10	I/O	Input/output A8. Referenced to V_{CCA} .
B1	21	21	I/O	Input/output B1. Referenced to V_{CCB} .
B2	20	20	I/O	Input/output B2. Referenced to V_{CCB} .
B3	19	19	I/O	Input/output B3. Referenced to V_{CCB} .
B4	18	18	I/O	Input/output B4. Referenced to V_{CCB} .
B5	17	17	I/O	Input/output B5. Referenced to V_{CCB} .
B6	16	16	I/O	Input/output B6. Referenced to V_{CCB} .
B7	15	15	I/O	Input/output B7. Referenced to V_{CCB} .
B8	14	14	I/O	Input/output B8. Referenced to V_{CCB} .
DIR	2	—	I	Direction-control input for 1 ports
GND	12, 13	11, 12, 13	—	Ground
OE	22	22	I	3-state output-mode enable. Pull $\overline{OE}$ high to place '2' outputs in 3-state mode. Referenced to V_{CCA} .
V_{CCA}	1	1	—	A-port power supply voltage. $1.2\text{ V} \leq V_{CCA} \leq 3.6\text{ V}$
V_{CCB}	23, 24	23, 24	—	B-port power supply voltage. $1.2\text{ V} \leq V_{CCB} \leq 3.6\text{ V}$
Thermal pad			—	The exposed thermal pad must be connected as a secondary GND or be left electrically open.

(1) I = input, O = output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V_{CCA}	Supply voltage		-0.5	4.6	V
V_{CCB}					
V_I	Input voltage ⁽²⁾	I/O ports (A port)	-0.5	4.6	V
		I/O ports (B port)	-0.5	4.6	V
		Control inputs	-0.5	4.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	A port	-0.5	4.6	V
		B port	-0.5	4.6	V
V_O	Voltage range applied to any output in the high or low state ^{(2) (3)}	A port	-0.5	$(V_{CCA} + 0.5)$	V
		B port	-0.5	$(V_{CCB} + 0.5)$	V
I_{IK}	Input clamp current	$V_I < 0$		-50	mA
I_{OK}	Output clamp current	$V_O < 0$		-50	mA
I_O	Continuous output current			±50	mA
	Continuous current through V_{CCA} , V_{CCB} , or GND			±100	mA
T_J	Junction temperature			150	°C
T_{stg}	Storage temperature		-65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The device withstands voltages in excess of input voltage and output negative-voltage ratings while operating within the input and output current ratings.
- (3) The device withstands voltages in excess of the output positive-voltage rating up to 4.6 V maximum while operating within the output current rating.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 Classification Level H2 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per AEC Q100-011 Classification Level C3B	±750	

- (1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

5.3 Recommended Operating Conditions

See (1) (2) (3)

			V _{CCI}	V _{CCO}	MIN	MAX	UNIT
V _{CCA}	Supply voltage				1.2	3.6	V
V _{CCB}	Supply voltage				1.2	3.6	V
V _{IH}	High-level input voltage	Data inputs	1.2 V to 1.95 V		V _{CCI} × 0.65		V
			1.95 V to 2.7 V		1.6		
			2.7 V to 3.6 V		2		
V _{IL}	Low-level input voltage	Data inputs	1.2 V to 1.95 V		V _{CCI} × 0.35		V
			1.95 V to 2.7 V		0.7		
			2.7 V to 3.6 V		0.8		
V _{IH}	High-level input voltage	DIR (referenced to V _{CCA})	1.2 V to 1.95 V		V _{CCA} × 0.65		V
			1.95 V to 2.7 V		1.6		
			2.7 V to 3.6 V		2		
V _{IL}	Low-level input voltage	DIR (referenced to V _{CCA})	1.2 V to 1.95 V		V _{CCA} × 0.35		V
			1.95 V to 2.7 V		0.7		
			2.7 V to 3.6 V		0.8		
V _I	Input voltage				0	3.6	V
V _O	Output voltage	Active state			0	V _{CCO}	V
		3-state			0	3.6	
I _{OH}	High-level output current			1.2 V		–3	mA
				1.4 V to 1.6 V		–6	
				1.65 V to 1.95 V		–8	
				2.3 V to 2.7 V		–9	
				3 V to 3.6 V		–12	
I _{OL}	Low-level output current			1.2 V		3	mA
				1.4 V to 1.6 V		6	
				1.65 V to 1.95 V		8	
				2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt / Δv	Input transition rise or fall rate					5	ns / V
T _A	Operating free-air temperature				–40	125	°C

- (1) V_{CCI} is the V_{CC} associated with the input port.
(2) V_{CCO} is the V_{CC} associated with the output port.
(3) Hold all unused data inputs of the device at V_{CCI} or GND for proper device operation. See the TI application report, [Implications of Slow or Floating CMOS Inputs](#), SCBA004.

5.4 Thermal Information

THERMAL METRIC		SN74AVC8T245-Q1		UNIT
		RHL (VQFN)	PW (TSSOP)	
		24 PINS	24 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	36.8	93.1	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	32.5	36.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	15.7	48.4	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.7	93.1	°C/W
ψ_{JB}	Junction-to-board characterization parameter	15.6	48.0	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	5.6	N/A	°C/W

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)^{(2) (1)}

PARAMETER		TEST CONDITIONS	V_{CCA}	V_{CCB}	T_A	MIN	TYP	MAX	UNIT
V_{OH}		$V_I = V_{IH}$	1.2 V to 3.6 V	1.2 V to 3.6 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	$V_{CCO} - 0.2$			V
			1.2 V	1.2 V	$T_A = 25^\circ\text{C}$	0.95			
			1.4 V	1.4 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	1			
			1.65 V	1.65 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	1.2			
			2.3 V	2.3 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	1.75			
			3 V	3 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$	2.3			
V_{OL}		$V_I = V_{IL}$	1.2 V to 3.6 V	1.2 V to 3.6 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			0.2	V
			1.2 V	1.2 V	$T_A = 25^\circ\text{C}$			0.15	
			1.4 V	1.4 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			0.35	
			1.65 V	1.65 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			0.45	
			2.3 V	2.3 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			0.55	
			3 V	3 V	$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			0.7	
I_I	Control inputs	$V_I = V_{CCA}$ or GND	1.2 V to 3.6 V	1.2 V to 3.6 V	$T_A = 25^\circ\text{C}$	± 0.02	± 0.25		μA
					$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		± 1		
I_{off}	A or B port	V_I or $V_O = 0$ to 3.6 V	0 V	0 V to 3.6 V	$T_A = 25^\circ\text{C}$		± 0.1	± 1	μA
					$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		± 5		
			0 V to 3.6 V	0 V	$T_A = 25^\circ\text{C}$		± 0.1	± 1	
					$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$		± 5		
$I_{OZ}^{(3)}$	A or B port	$V_O = V_{CCO}$ or GND, $V_I = V_{CCI}$ or GND, $OE = V_{IH}$	3.6 V	3.6 V	$T_A = 25^\circ\text{C}$		± 0.5	± 2.5	μA
					$T_A = -40^\circ\text{C}$ to $+125^\circ\text{C}$			± 5	

5.5 Electrical Characteristics (続き)

over recommended operating free-air temperature range (unless otherwise noted)⁽²⁾ (1)

PARAMETER		TEST CONDITIONS	V _{CCA}	V _{CCB}	T _A	MIN	TYP	MAX	UNIT
I _{CCA}		V _I = V _{CCI} or GND ⁽³⁾ , I _O = 0	1.2 V to 3.6 V	1.2 V to 3.6 V	T _A = –40°C to +125°C			15	μA
			0 V	3.6 V	T _A = –40°C to +125°C		–2		
			3.6 V	0 V	T _A = –40°C to +125°C		15		
I _{CCB}		V _I = V _{CCI} or GND ⁽³⁾ , I _O = 0	1.2 V to 3.6 V	1.2 V to 3.6 V	T _A = –40°C to +125°C			15	μA
			0 V	3.6 V	T _A = –40°C to +125°C		15		
			3.6 V	0 V	T _A = –40°C to +125°C		–2		
I _{CCA} + I _{CCB}		V _I = V _{CCI} or GND, I _O = 0	1.2 V to 3.6 V	1.2 V to 3.6 V	T _A = –40°C to +125°C			25	μA
C _i	Control inputs	V _I = 3.3 V or GND	3.3 V	3.3 V	T _A = 25°C		3.5		pF
C _{io}	A or B port	V _O = 3.3 V or GND	3.3 V	3.3 V	T _A = 25°C		6		pF

(1) V_{CCI} is the V_{CC} associated with the input port.

(2) V_{CCO} is the V_{CC} associated with the output port.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

5.6 Switching Characteristics: V_{CCA} = 1.2 V

over recommended operating free-air temperature range, V_{CCA} = 1.2 V (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CCB}	TYP	UNIT
t _{PLH} , t _{PHL}	A	B	V _{CCB} = 1.2 V	3.1	ns
			V _{CCB} = 1.5 V	2.6	
			V _{CCB} = 1.8 V	2.5	
			V _{CCB} = 2.5 V	3	
			V _{CCB} = 3.3 V	3.5	
t _{PLH} , t _{PHL}	B	A	V _{CCB} = 1.2 V	3.1	ns
			V _{CCB} = 1.5 V	2.7	
			V _{CCB} = 1.8 V	2.5	
			V _{CCB} = 2.5 V	2.4	
			V _{CCB} = 3.3 V	2.3	
t _{PZH} , t _{PZL}	$\overline{\text{OE}}$	A	V _{CCB} = 1.2 V	5.3	ns
			V _{CCB} = 1.5 V		
			V _{CCB} = 1.8 V		
			V _{CCB} = 2.5 V		
			V _{CCB} = 3.3 V		
t _{PZH} , t _{PZL}	$\overline{\text{OE}}$	B	V _{CCB} = 1.2 V	5.1	ns
			V _{CCB} = 1.5 V	4	
			V _{CCB} = 1.8 V	3.5	
			V _{CCB} = 2.5 V	3.2	
			V _{CCB} = 3.3 V	3.1	

5.6 Switching Characteristics: $V_{CCA} = 1.2\text{ V}$ (続き)

over recommended operating free-air temperature range, $V_{CCA} = 1.2\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	TYP	UNIT
t_{PHZ} , t_{PLZ}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$	4.8	ns
			$V_{CCB} = 1.5\text{ V}$		
			$V_{CCB} = 1.8\text{ V}$		
			$V_{CCB} = 2.5\text{ V}$		
			$V_{CCB} = 3.3\text{ V}$		
t_{PHZ} , t_{PLZ}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$	4.7	ns
			$V_{CCB} = 1.5\text{ V}$	4	
			$V_{CCB} = 1.8\text{ V}$	4.1	
			$V_{CCB} = 2.5\text{ V}$	4.3	
			$V_{CCB} = 3.3\text{ V}$	5.1	

5.7 Switching Characteristics: $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2\text{ V}$		3.1		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		14.7	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		13.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		13.9	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		17.2	
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2\text{ V}$		3.1		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		14.7	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		14.2	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		13.5	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		13.2	
t_{PZH} , t_{PZL}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		5.3		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		20.5	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		20.5	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		20.5	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		20.5	
t_{PZH} , t_{PZL}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		5.1		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		18.6	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		17.7	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		15.1	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		14.4	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		4.8		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		20.3	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		20.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		20.3	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		20.3	

5.7 Switching Characteristics: $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$ (続き)

over recommended operating free-air temperature range, $V_{CCA} = 1.5\text{ V} \pm 0.1\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	MIN	TYP	MAX	UNIT
t_{PHZ} , t_{PLZ}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		4.7		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		20.0	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		18.6	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		17.9	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		18.9	

5.8 Switching Characteristics: $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 1.8\text{ V} \pm 0.15\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2\text{ V}$		2.5		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		14.2	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		13.0	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		12.3	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.1	
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2\text{ V}$		2.5		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		13.3	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		13.0	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		12.1	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		11.8	
t_{PZH} , t_{PZL}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		3		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		17.2	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		17.2	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		17.2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		17.2	
t_{PZH} , t_{PZL}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		4.6		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		19.6	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		17.0	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		14.2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		13.2	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		2.8		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		17.7	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		17.7	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		17.7	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		17.7	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		3.9		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		18.9	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		17.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		15.8	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		15.4	

5.9 Switching Characteristics: $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 2.5\text{ V} \pm 0.2\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2\text{ V}$		2.4		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		13.5	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		12.1	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		10.7	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		10.2	
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2\text{ V}$		3		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		13.9	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		12.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		10.7	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		10.4	
t_{PZH} , t_{PZL}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		2.2		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		13.7	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		13.7	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		13.7	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		13.7	
t_{PZH} , t_{PZL}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		4.5		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		19.1	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		16.5	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		13.3	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.3	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		1.8		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		14.2	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		14.2	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		14.2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		14.2	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		3.6		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		17.7	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		16.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		14.2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.1	

5.10 Switching Characteristics: $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$

over recommended operating free-air temperature range, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	A	B	$V_{CCB} = 1.2\text{ V}$		2.3		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		13.2	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		11.1	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		10.4	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		9.7	

5.10 Switching Characteristics: $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$ (続き)

over recommended operating free-air temperature range, $V_{CCA} = 3.3\text{ V} \pm 0.3\text{ V}$ (see [Figure 6-1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CCB}	MIN	TYP	MAX	UNIT
t_{PLH} , t_{PHL}	B	A	$V_{CCB} = 1.2\text{ V}$		3.5		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		17.2	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		12.1	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		10.2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		9.7	
t_{PZH} , t_{PZL}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		2		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		12.3	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		12.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		12.3	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.3	
t_{PZH} , t_{PZL}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		4.5		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		18.9	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		16.1	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		13.2	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.3	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	A	$V_{CCB} = 1.2\text{ V}$		1.7		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		12.3	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		12.3	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		12.3	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.3	
t_{PHZ} , t_{PLZ}	$\overline{OE}$	B	$V_{CCB} = 1.2\text{ V}$		3.4		ns
			$V_{CCB} = 1.5\text{ V} \pm 0.1\text{ V}$	0.5		17.4	
			$V_{CCB} = 1.8\text{ V} \pm 0.15\text{ V}$	0.5		15.8	
			$V_{CCB} = 2.5\text{ V} \pm 0.2\text{ V}$	0.5		13.7	
			$V_{CCB} = 3.3\text{ V} \pm 0.3\text{ V}$	0.5		12.6	

5.11 Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER			TEST CONDITIONS	V _{CCA}	TYP	UNIT	
C _{pdA} ⁽¹⁾	A to B	Outputs enabled	C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V	1	pF	
				V _{CCA} = V _{CCB} = 1.5 V			
				V _{CCA} = V _{CCB} = 1.8 V			
				V _{CCA} = V _{CCB} = 2.5 V			
				V _{CCA} = V _{CCB} = 3.3 V			
	Outputs disabled		C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V	1		
				V _{CCA} = V _{CCB} = 1.5 V			
				V _{CCA} = V _{CCB} = 1.8 V			
				V _{CCA} = V _{CCB} = 2.5 V			
				V _{CCA} = V _{CCB} = 3.3 V			
	B to A	Outputs enabled		C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V		12
					V _{CCA} = V _{CCB} = 1.5 V		12
					V _{CCA} = V _{CCB} = 1.8 V		12
					V _{CCA} = V _{CCB} = 2.5 V		13
					V _{CCA} = V _{CCB} = 3.3 V		14
Outputs disabled			C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V	1		
				V _{CCA} = V _{CCB} = 1.5 V			
				V _{CCA} = V _{CCB} = 1.8 V			
				V _{CCA} = V _{CCB} = 2.5 V			
				V _{CCA} = V _{CCB} = 3.3 V			
C _{pdB} ⁽¹⁾	A to B	Outputs enabled	C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V	12	pF	
				V _{CCA} = V _{CCB} = 1.5 V	12		
				V _{CCA} = V _{CCB} = 1.8 V	12		
				V _{CCA} = V _{CCB} = 2.5 V	13		
				V _{CCA} = V _{CCB} = 3.3 V	14		
	Outputs disabled		C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V	1		
				V _{CCA} = V _{CCB} = 1.5 V			
				V _{CCA} = V _{CCB} = 1.8 V			
				V _{CCA} = V _{CCB} = 2.5 V			
				V _{CCA} = V _{CCB} = 3.3 V			
	B to A	Outputs enabled		C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V		1
					V _{CCA} = V _{CCB} = 1.5 V		
					V _{CCA} = V _{CCB} = 1.8 V		
					V _{CCA} = V _{CCB} = 2.5 V		
					V _{CCA} = V _{CCB} = 3.3 V		
Outputs disabled			C _L = 0, f = 10 MHz, t _r = t _f = 1 ns	V _{CCA} = V _{CCB} = 1.2 V	1		
				V _{CCA} = V _{CCB} = 1.5 V			
				V _{CCA} = V _{CCB} = 1.8 V			
				V _{CCA} = V _{CCB} = 2.5 V			
				V _{CCA} = V _{CCB} = 3.3 V			

(1) Power dissipation capacitance per transceiver

5.12 Typical Total Static Current Consumption ($I_{CCA} + I_{CCB}$)

V_{CCB}	V_{CCA}						UNIT
	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	
0 V	0	<0.5	<0.5	<0.5	<0.5	<0.5	μA
1.2 V	<0.5	<1	<1	<1	<1	1	μA
1.5 V	<0.5	<1	<1	<1	<1	1	μA
1.8 V	<0.5	<1	<1	<1	<1	<1	μA
2.5 V	<0.5	1	<1	<1	<1	<1	μA
3.3 V	<0.5	1	<1	<1	<1	<1	μA

5.13 Typical Characteristics

$T_A = 25^\circ\text{C}$

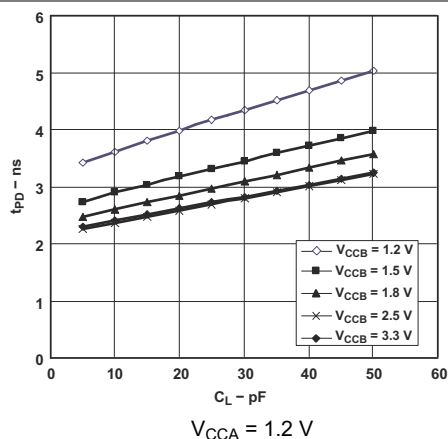


図 5-1. Typical Propagation Delay (A to B) vs Load Capacitance

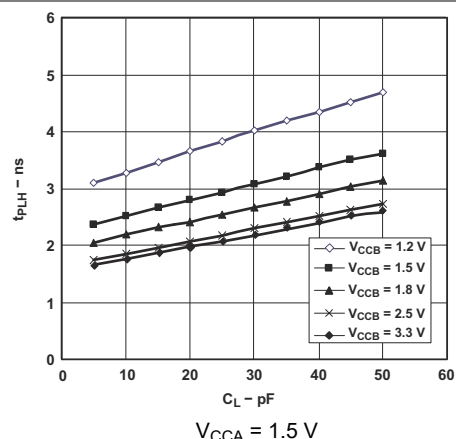


図 5-2. Typical Propagation Delay (A to B) vs Load Capacitance

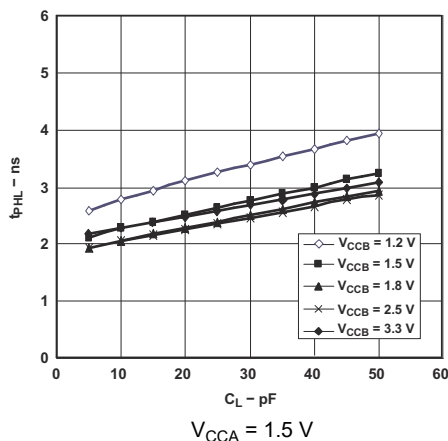


図 5-3. Typical Propagation Delay (A to B) vs Load Capacitance

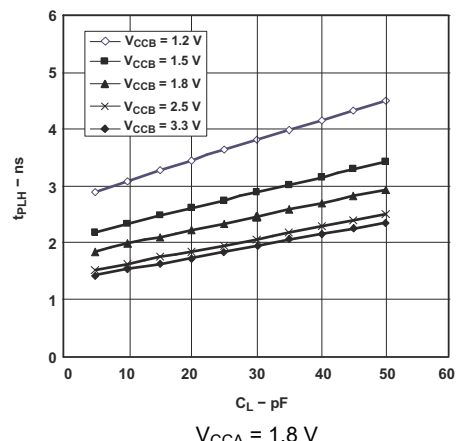


図 5-4. Typical Propagation Delay (A to B) vs Load Capacitance

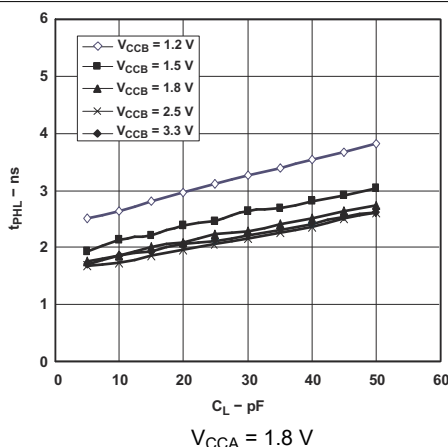


図 5-5. Typical Propagation Delay (A to B) vs Load Capacitance

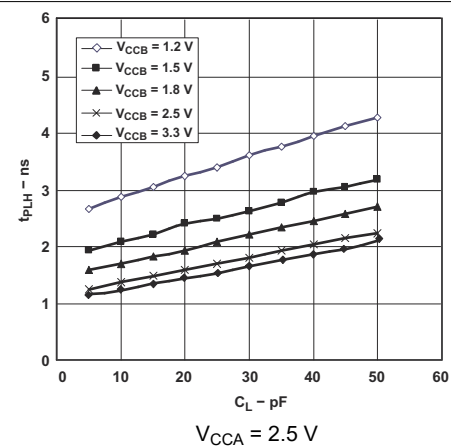


図 5-6. Typical Propagation Delay (A to B) vs Load Capacitance

5.13 Typical Characteristics (continued)

$T_A = 25^\circ\text{C}$

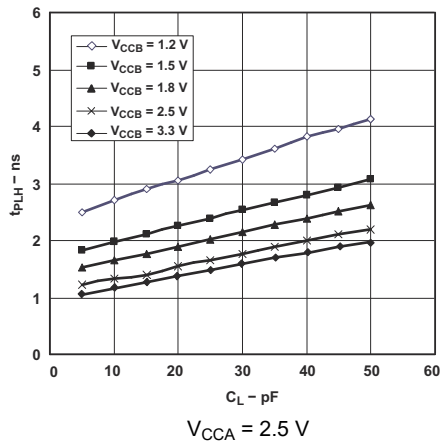


Figure 5-7. Typical Propagation Delay (A to B) vs Load Capacitance

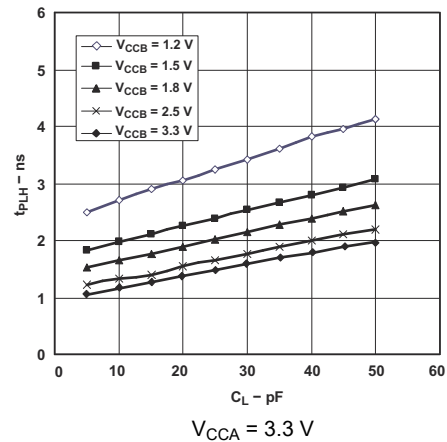


Figure 5-8. Typical Propagation Delay (A to B) vs Load Capacitance

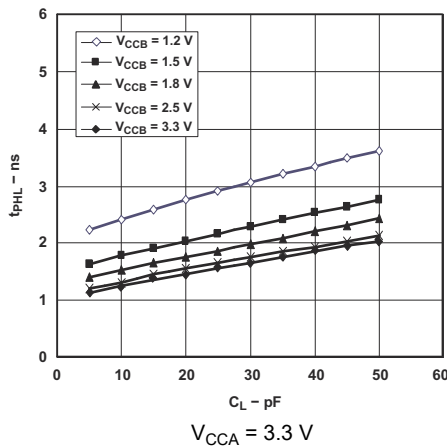


Figure 5-9. Typical Propagation Delay (A to B) vs Load Capacitance

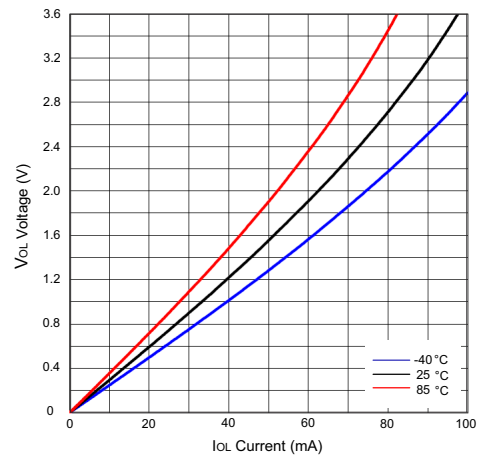


Figure 5-10. Low-Level Output Voltage (V_{OL}) vs Low-Level Current (I_{OL})

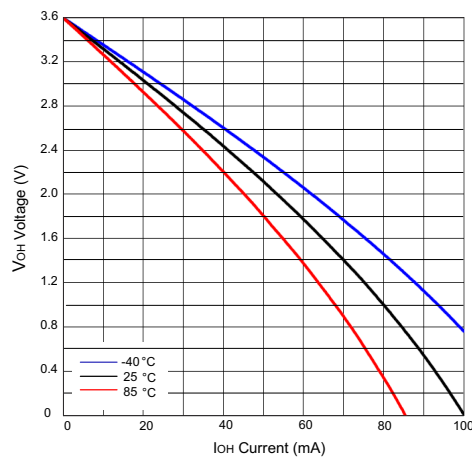
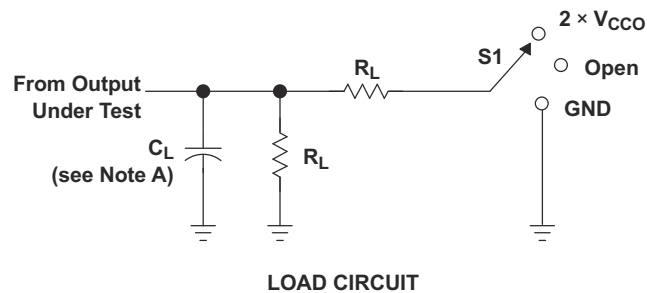


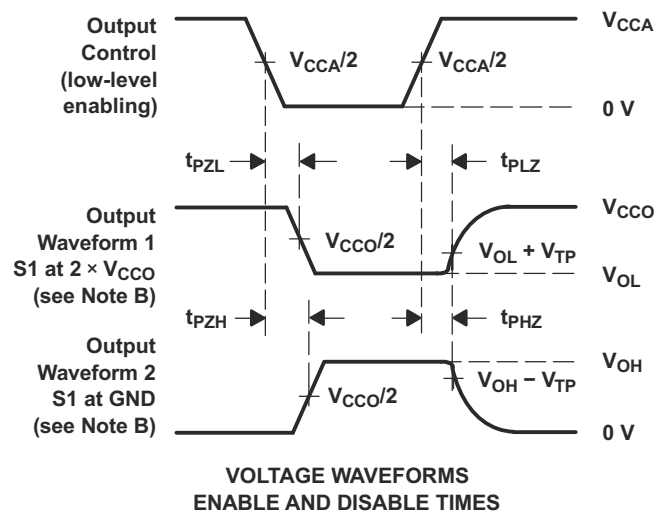
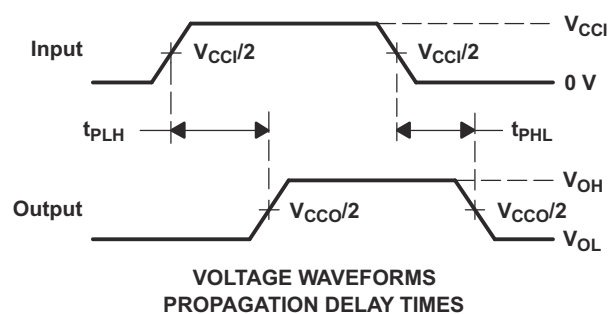
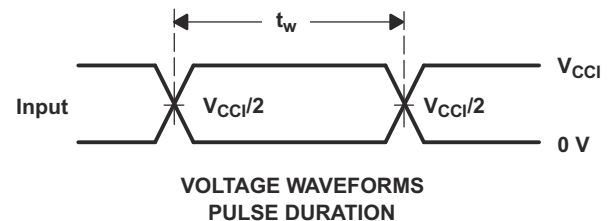
Figure 5-11. High-Level Output Voltage (V_{OH}) vs High-Level Current (I_{OH})

6 Parameter Measurement Information



V_{CCO}	C_L	R_L	V_{TP}
1.2 V	15 pF	2 k Ω	0.1 V
1.5 V $\pm$ 0.1 V	15 pF	2 k Ω	0.1 V
1.8 V $\pm$ 0.15 V	15 pF	2 k Ω	0.15 V
2.5 V $\pm$ 0.2 V	15 pF	2 k Ω	0.15 V
3.3 V $\pm$ 0.3 V	15 pF	2 k Ω	0.3 V

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	$2 \times V_{CCO}$
t_{PHZ}/t_{PZH}	GND



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $dv/dt \geq 1$ V/ns.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - V_{CCI} is the V_{CC} associated with the input port.
 - V_{CCO} is the V_{CC} associated with the output port.

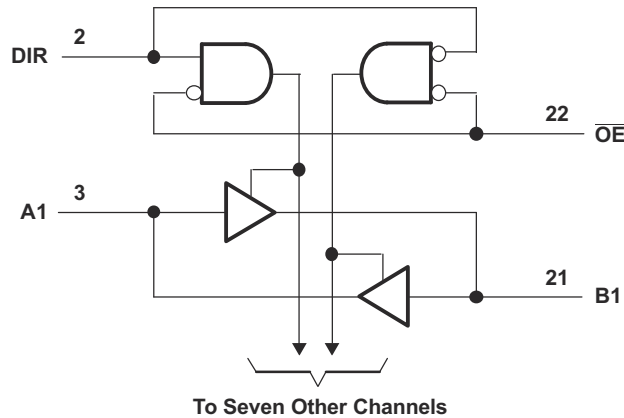
图 6-1. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SN74AVC8T245-Q1 is an 8-bit, dual-supply noninverting bidirectional voltage level translation device. V_{CCA} supports the Ax pins and control pins (DIR and $\overline{OE}$), and V_{CCB} supports the Bx pins. The A port can accept I/O voltages ranging from 1.2 V to 3.6 V, while the B port can accept I/O voltages from 1.2 V to 3.6 V. A high on DIR allows data transmission from Ax to Bx and a low on DIR allows data transmission from Bx to Ax when $\overline{OE}$ is set to low. When $\overline{OE}$ is set to high, both Ax and Bx pins are in the high-impedance state.

7.2 Functional Block Diagram



7-1. Logic Diagram (Positive Logic)

7.3 Feature Description

7.3.1 Fully Configurable Dual-Rail Design

Both V_{CCA} and V_{CCB} can be supplied at any voltage between 1.2 V and 3.6 V; thus, making the device an excellent choice for translating between any of the low voltage nodes (1.2 V, 1.8 V, 2.5 V, and 3.3 V).

7.3.2 Supports High Speed Translation

The SN74AVC8T245-Q1 device can support high data rate applications. The translated signal data rate can be up to 380Mbps when the signal is translated from 1.8 V to 3.3 V.

7.3.3 I_{off} Supports Partial-Power-Down Mode Operation

I_{off} prevents backflow current by disabling I/O output circuits when the device is in partial-power-down mode.

7.4 Device Functional Modes

表 7-1 lists the functional modes of the device.

表 7-1. Function Table
(Each 8-Bit Section)

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	All outputs Hi-Z

8 Application and Implementation

注

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8.1 Application Information

The SN74AVC8T245-Q1 device can be used in level-translation applications for interfacing devices or systems operating at different interface voltages with one another. The SN74AVC8T245-Q1 device is an excellent choice for applications where a push-pull driver is connected to the data I/Os. The maximum data rate can be up to 320Mbps when the device translates a signal from 1.8 V to 3.3 V.

8.2 Typical Application

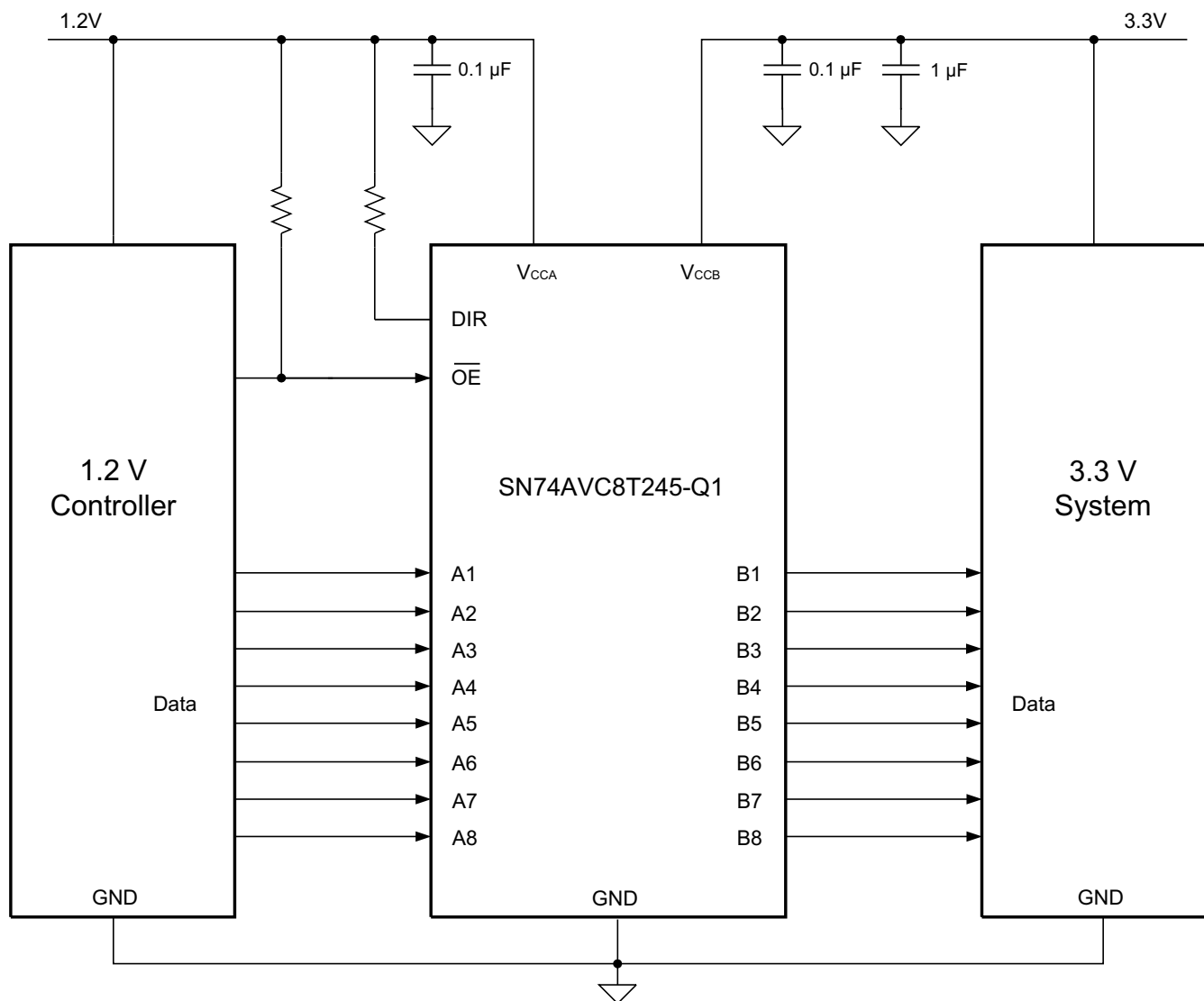


図 8-1. Typical Application Diagram

8.2.1 Design Requirements

表 8-1 lists the parameters for this design example.

表 8-1. Design Parameters

DESIGN PARAMETER	EXAMPLE VALUE
Input voltage range	1.2 V
Output voltage range	3.3 V

8.2.2 Detailed Design Procedure

To begin the design process, determine the following:

- Input voltage range
 - Use the supply voltage of the device that is driving the SN74AVC8T245-Q1 device to determine the input voltage range. For a valid logic high, the value must exceed the V_{IH} of the input port. For a valid logic low, the value must be less than the V_{IL} of the input port. For this example, the input voltage is 1.2 V.
- Output voltage range
 - Use the supply voltage of the device that the SN74AVC8T245-Q1 device is driving to determine the output voltage range. For this example, the output voltage is 3.3 V.

8.2.3 Application Curve

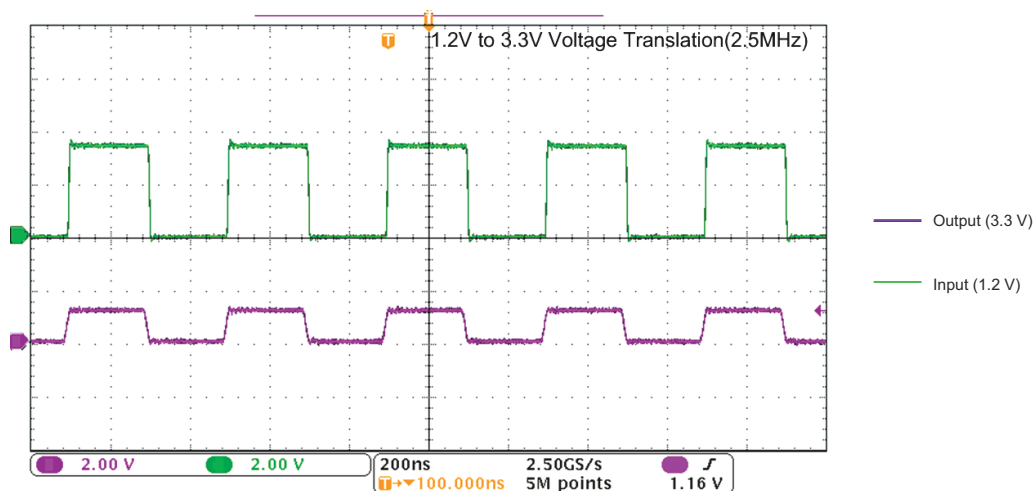


図 8-2. Translation Up (1.2 V to 3.3 V) at 2.5 MHz

8.3 Power Supply Recommendations

The SN74AVC8T245-Q1 device uses two separate configurable power-supply rails: V_{CCA} and V_{CCB} . V_{CCA} accepts any supply voltage from 1.2 V to 3.6 V, and V_{CCB} accepts any supply voltage from 1.2 V to 3.6 V. The A port and B port are designed to track V_{CCA} and V_{CCB} respectively, allowing for low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

V_{CCA} supplies the output-enable ($\overline{OE}$) input circuit in this design; when the $\overline{OE}$ input is high, all outputs are placed in the high-impedance state. To put the outputs in the high-impedance state during power up or power down, the $\overline{OE}$ input pin must be tied to V_{CCA} through a pullup resistor and must not be enabled until V_{CCA} and V_{CCB} are fully ramped and stable. The current-sinking capability of the driver determines the minimum value of the pullup resistor to V_{CCA} .

8.4 Layout

8.4.1 Layout Guidelines

For device reliability, it is recommended to follow common printed-circuit board layout guidelines:

- Use bypass capacitors on power supplies.
- Use short trace lengths to avoid excessive loading.
- Place pads on the signal paths for loading capacitors or pullup resistors to adjust signal rise and fall times, depending on the system requirements.

8.4.2 Layout Example

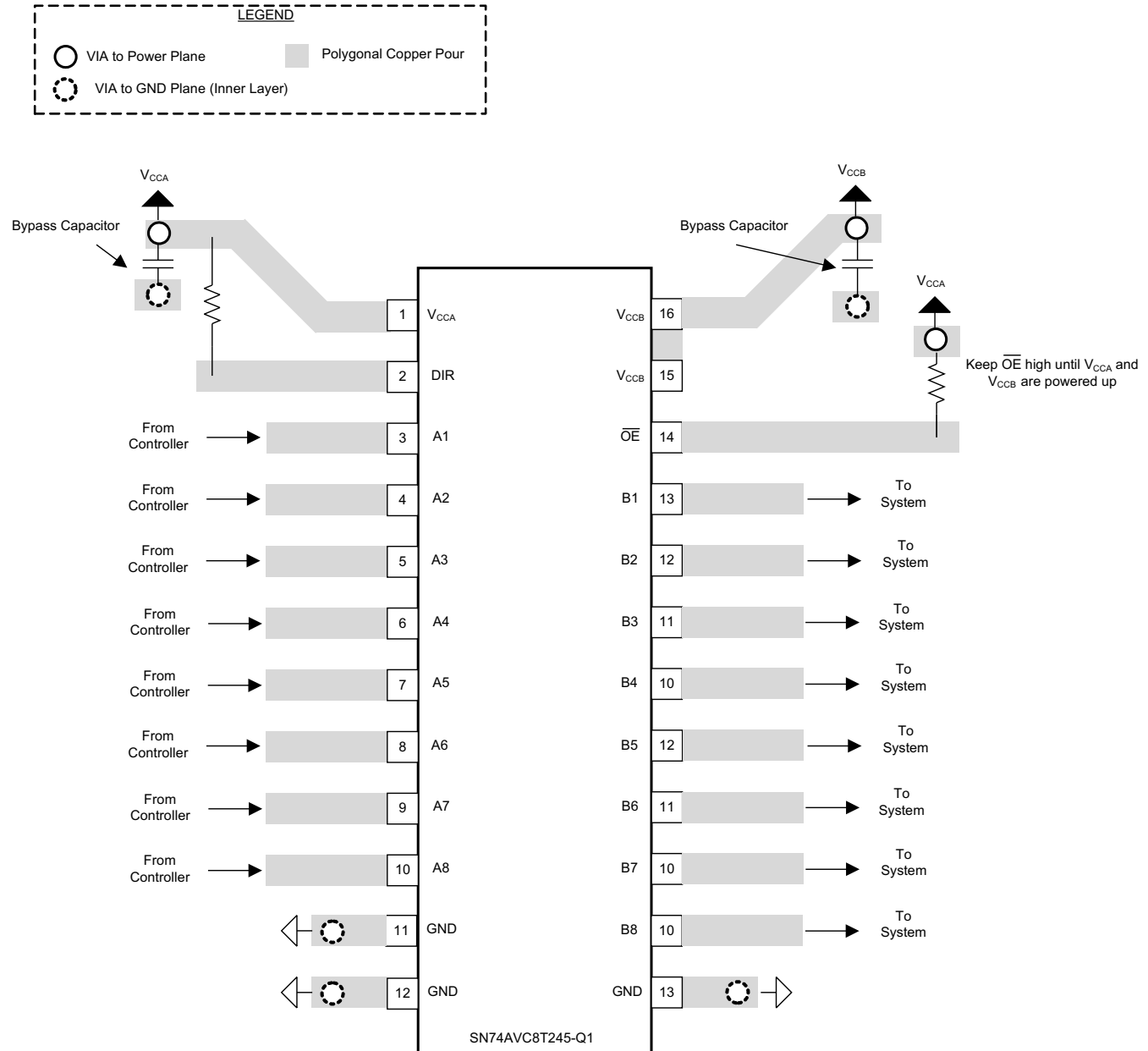


図 8-3. SN74AVC8T245-Q1 Layout Diagram

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [Implications of Slow or Floating CMOS Inputs Application Note](#)
- Texas Instruments, [Understanding and Interpreting Standard-Logic Data Sheets Application Note](#)
- Texas Instruments, [Introduction to Logic Application Note](#)
- Texas Instruments, [Voltage Translation Between 3.3-V, 2.5-V, 1.8-V, and 1.5-V Logic Standards Application Note](#)
- Texas Instruments, [AVC Advanced Very-Low-Voltage CMOS Logic Data Book User's Guide](#)

9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.3 サポート・リソース

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9.6 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision D (October 2017) to Revision E (November 2023)	Page
• 文書全体にわたって表、図、相互参照の採番方法を更新.....	1
• Updated the thermal information for the <i>RHL</i> package and updated the information for the <i>PW</i> package.....	6
Changes from Revision C (March 2016) to Revision D (October 2017)	Page
• Added Junction temperature, T_J in <i>Absolute Maximum Ratings</i> table.....	4
• Deleted 2DIR and 2 $\overline{OE}$ from <i>Overview</i>	17

Changes from Revision B (December 2012) to Revision C (January 2016)**Page**

- 「ESD 定格」表、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加。 [1](#)
- 「注文情報」表を削除 [1](#)

Changes from Revision A (June 2011) to Revision B (December 2012)**Page**

- 「特長」リストに複数の箇条書き項目を追加 [1](#)
- Added *Pin Functions* table to the data sheet [3](#)
- Deleted θ_{JA} row from *Absolute Maximum Ratings* table [4](#)
- Changed ESD ratings [4](#)
- Added Thermal Information table [6](#)
- Added Figure 7-10 and Figure 7-11 to the *Typical Characteristics* section [14](#)

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CAVC8T245QRHLRQ1	ACTIVE	VQFN	RHL	24	1000	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	WE245Q	Samples
SN74AVC8T245QPWRQ1	ACTIVE	TSSOP	PW	24	2000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	WE245Q	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74AVC8T245-Q1 :

- Catalog : [SN74AVC8T245](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CAVC8T245QRHLRQ1	VQFN	RHL	24	1000	180.0	12.4	3.8	5.8	1.2	8.0	12.0	Q1
SN74AVC8T245QPWRQ1	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

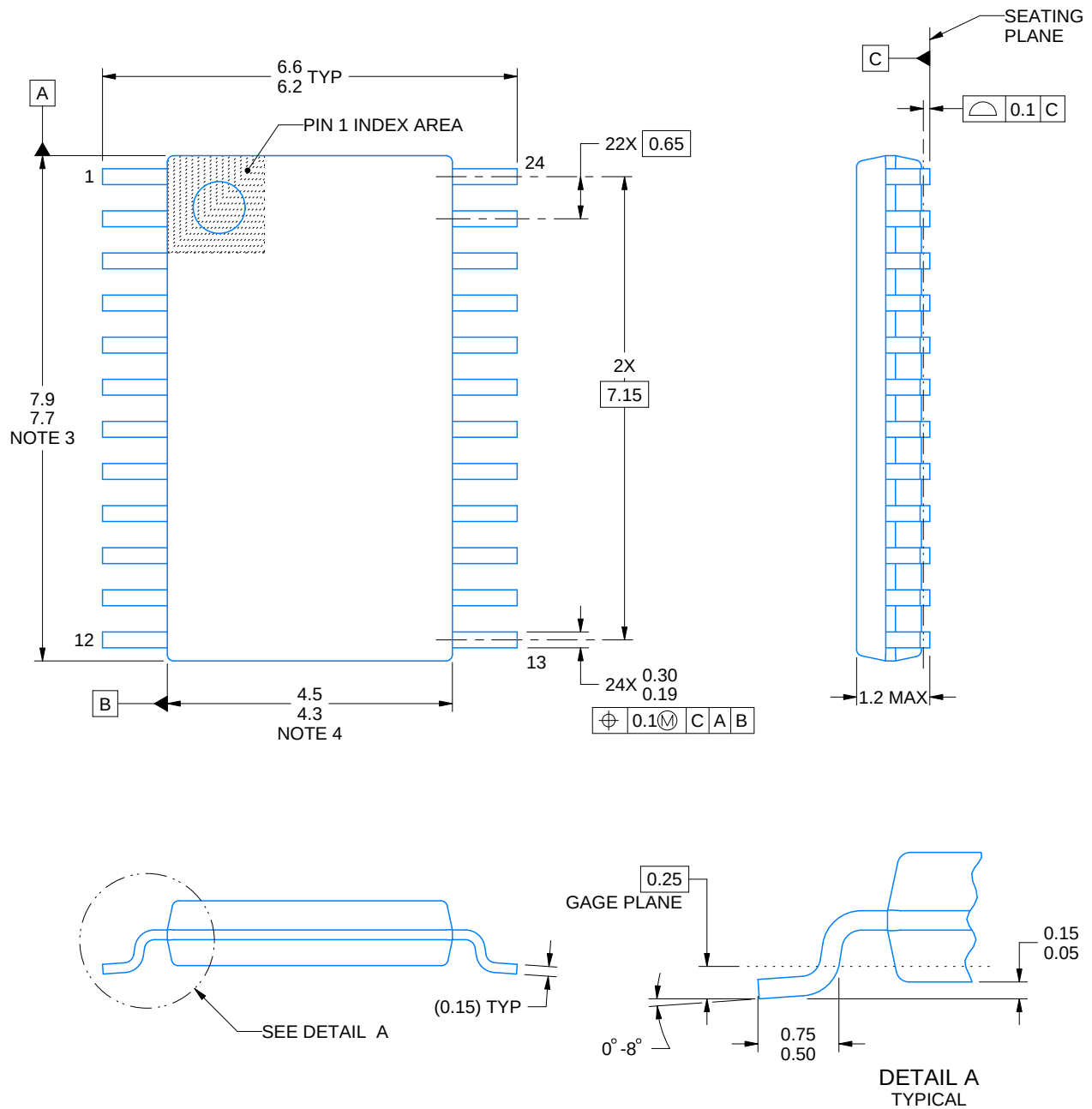
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CAVC8T245QRHLRQ1	VQFN	RHL	24	1000	210.0	185.0	35.0
SN74AVC8T245QPWRQ1	TSSOP	PW	24	2000	356.0	356.0	35.0

PW0024A

PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220208/A 02/2017

NOTES:

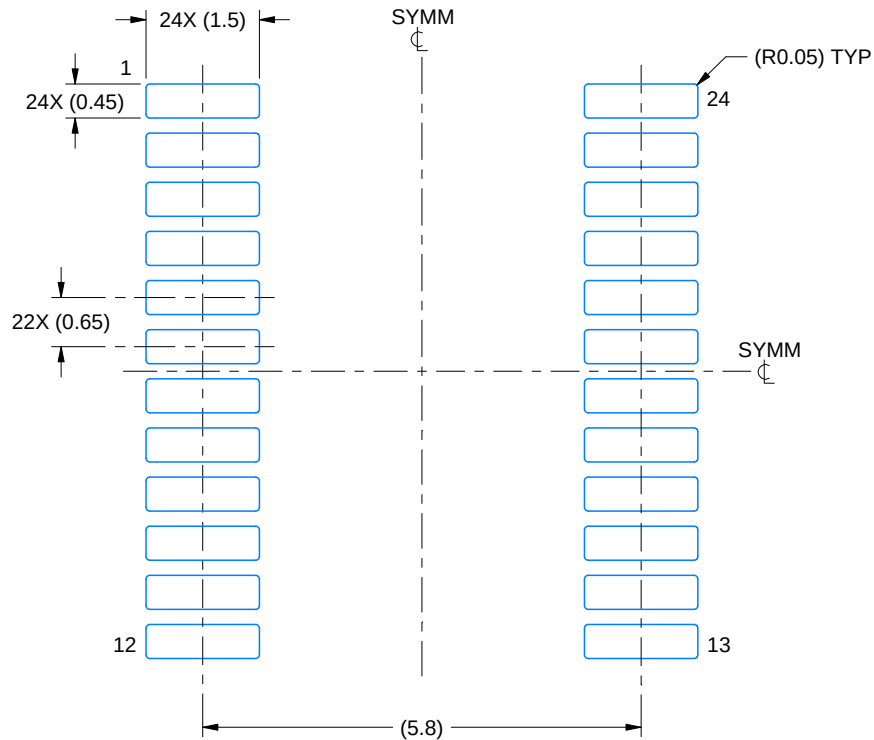
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

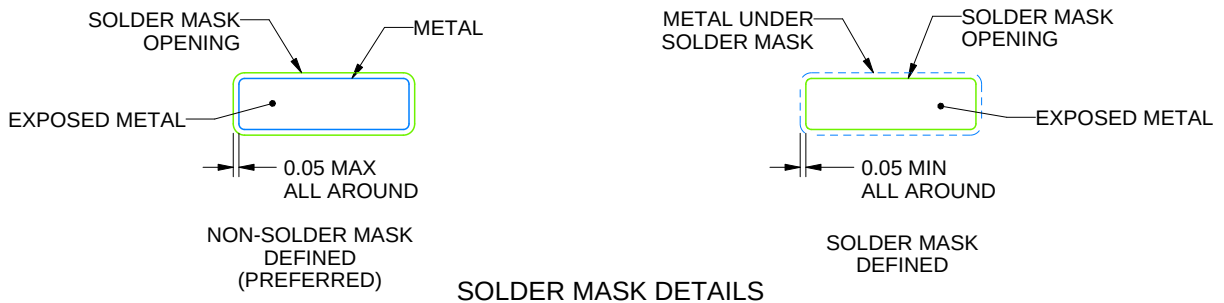
PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

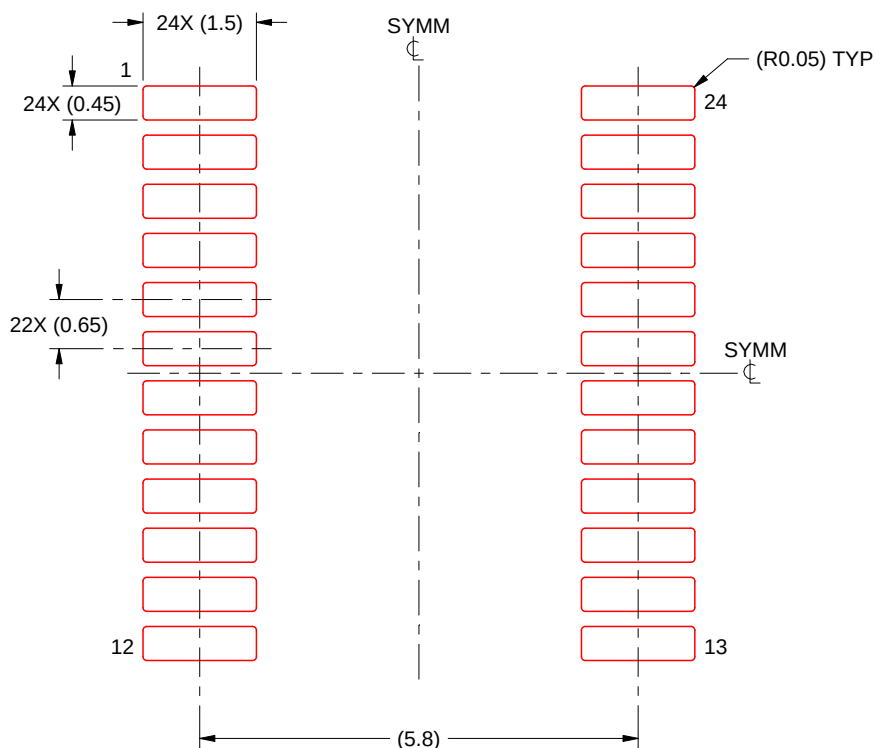
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0024A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

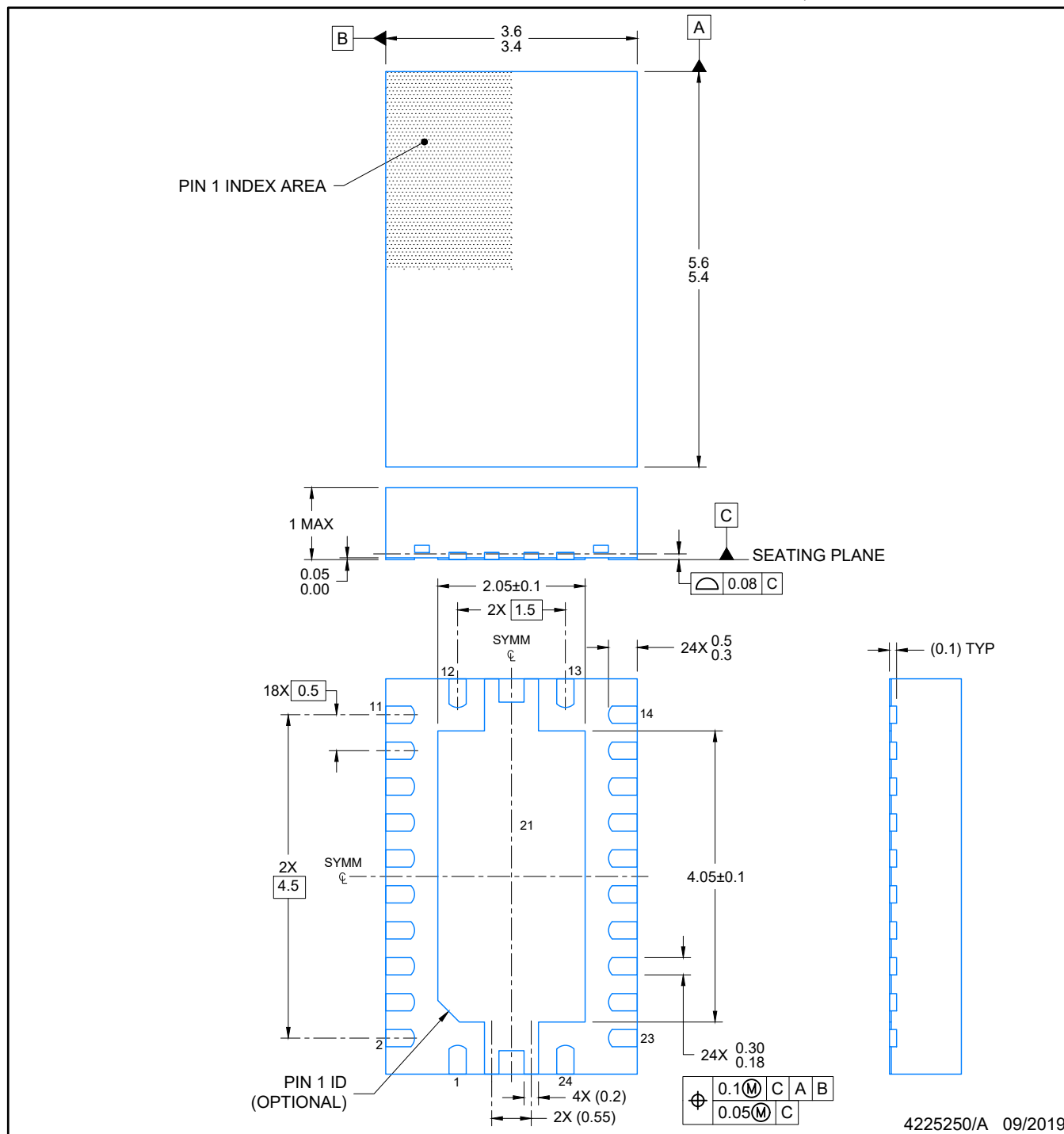


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

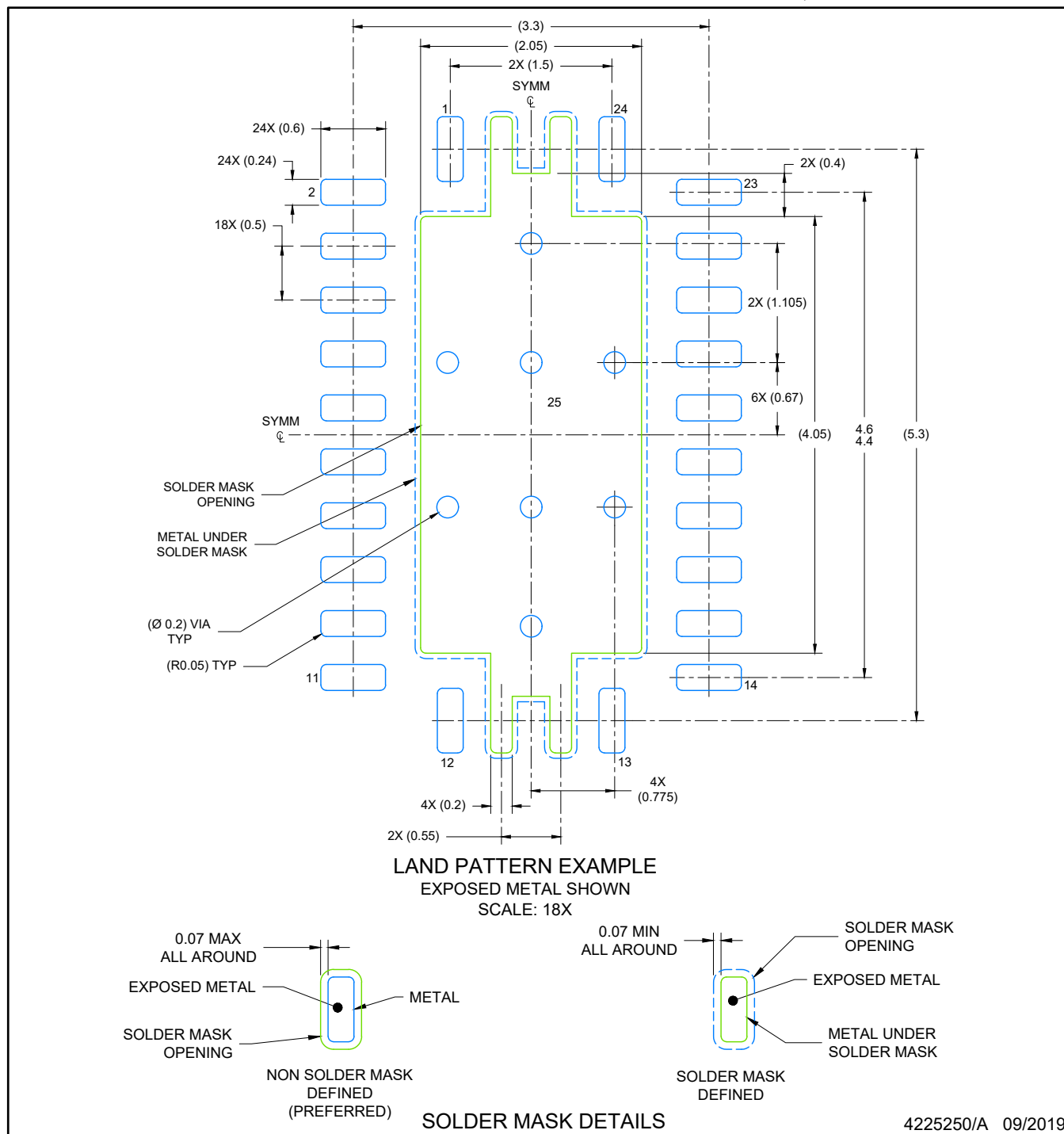
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slue271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

VQFN - 1 mm max height

[illegible]

EXPOSED PAD
80% PRINTED COVERAGE BY AREA
SCALE: 18X



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